

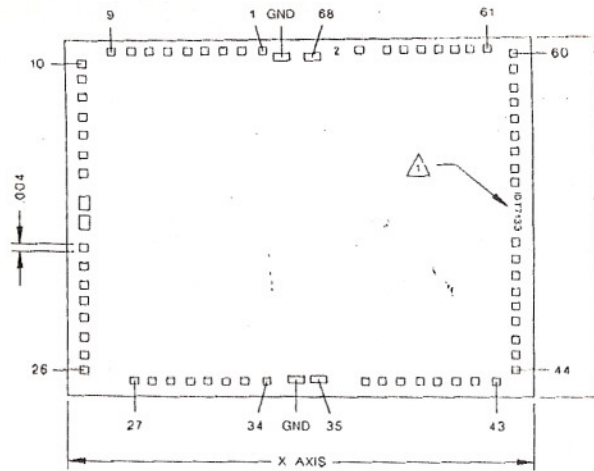


Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



I.D.T. - IDT7133

1 Die Mask I.D. Number - 7133 Z

2 Metallized Landmark

Dimensions	X Axis	Y Axis	Tolerance	Technical Information
Glass to Glass	.249 inch	.247 inch	Nominal	Pad Metal: Al
Edge to Edge	.330 inch	.253 inch	+003 inch	Backside Material: Au
Manufacturer	.400 inch	.350 inch	Nominal	Backside Potential: VCC
Thickness	.020 inch		Nominal	
Bond Pads	.004 inch	.004 inch	Nominal	
Die Size	15/1 inch			

Topside Metal: Al

Backside: Si

Backside Potential:

Mask Ref:

Bond Pads : .004"

APPROVED BY: CB

MFG: IDT

DIE SIZE : .330" x .253"

THICKNESS: .020"

DATE: 2/7/01

P/N: IDT7133